

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-15. (Canceled)

16. (Currently Amended) Microcomponent ~~comprising~~comprising:
a hermetically-sealed microcavity having a top side, a left side, and a right side,
~~the microcavity delineated by a cover in which at least one hole is formed, and, on the~~
~~cover, a cover in which at least one hole is formed, the cover being one solid layer that~~
~~delineates the microcavity and encloses the top side, the left side, and the right side of the~~
~~microcavity,~~

a plug forming a unitary piece made of polymer covering only one hole and a part of
the cover over the periphery of the hole,

a sealing layer hermetically sealing the microcavity, the microcomponent comprising,
under the sealing layer, a plug covering the hole and a part of the cover over the periphery of
the hole, the sealing layer being disposed above the plug and the cover, the sealing layer and
the plug being formed by distinct materials, wherein the plug is made of polymer, the cover
encloses the top side, the left side, and the right side of the microcavity, and the cover is one
solid layer materials.

17. (Canceled)

18. (Previously Presented) Microcomponent according to claim 35, wherein the polymer is selected from photoresists and polyimide.

19-20. (Canceled)

21. (Previously Presented) Microcomponent according to claim 35, wherein the dimension of the hole is smaller than 5 micrometers.

22. (Previously Presented) Microcomponent according to claim 35, wherein the hole is arranged on the highest part of the microcavity.

23. (Previously Presented) Microcomponent according to claim 35, comprising a plurality of holes.

24. (Previously Presented) Microcomponent according to claim 35, wherein the thickness of the plug is comprised between 2 and 6 micrometers.

25. (Previously Presented) Microcomponent according to claim 35, wherein the plug comprises sloping sides.

26. (Previously Presented) Microcomponent according to claim 35, wherein the plug is non-hermetical.

27. (Previously Presented) Microcomponent according to claim 35, wherein the material of the sealing layer is selected from silicon dioxide, silicon nitride and metals.

28. (Previously Presented) Method for production of a hermetically-sealed microcavity of a microcomponent according to claim 35, successively comprising

- deposition of a sacrificial layer on a substrate,
- deposition of a first layer forming the cover, on the substrate and sacrificial layer,

- etching, in the cover, of at least one hole opening out onto the sacrificial layer,

- removal of the sacrificial layer, via the hole, so as to create the microcavity,
- deposition of the sealing layer, so as to seal the microcavity hermetically,

method comprising deposition of the plug covering the hole and a part of the cover over the periphery of the hole, after the sacrificial layer has been removed and before the sealing layer is deposited.

29. (Previously Presented) A Method for production of a hermetically-sealed microcavity of a microcomponent, successively comprising:

- deposition of a sacrificial layer on a substrate;
- deposition of a first layer forming the cover, on the substrate and sacrificial layer;
- etching, in the cover, of at least one hole opening out onto the sacrificial layer;
- removal of the sacrificial layer, via the hole, so as to create the microcavity;
- deposition of the sealing layer, so as to seal the microcavity hermetically;

the method comprising deposition of a plug covering the hole and a part of the cover over the periphery of the hole, after the sacrificial layer has been removed and before the sealing layer is deposited;

wherein the plug is made of phosphosilicate glass, and the plug is obtained by a method selected from solgel methods and cathode sputtering.

30. (Previously Presented) Method according to claim 28, wherein the plug is made of a porous material.

31. (Previously Presented) A Method for production of a hermetically-sealed microcavity of a microcomponent, successively comprising:

- deposition of a sacrificial layer on a substrate;
- deposition of a first layer forming the cover, on the substrate and sacrificial layer;
- etching, in the cover, of at least one hole opening out onto the sacrificial layer;
- removal of the sacrificial layer, via the hole, so as to create the microcavity;
- deposition of the sealing layer, so as to seal the microcavity hermetically;

the method comprising deposition of a plug covering the hole and a part of the cover over the periphery of the hole, after the sacrificial layer has been removed and before the sealing layer is deposited;

wherein the plug is made of a porous material; and

wherein, the porous material is a photoresist, and the method comprises a high temperature annealing step.

32. (Previously Presented) Method according to claim 30, wherein the method comprises a pumping step of the gas contained in the microcavity, through the porous material, before the sealing layer is deposited.

33. (Previously Presented) Microcomponent according to claim 16, wherein the microcavity encloses an electromechanical microsystem.

34. (Currently Amended) Microcomponent comprisingcomprising:
a hermetically-sealed microcavity, ~~delineated by a cover in which at least one hole is formed, and, on the cover,~~

a cover in which at least one hole is formed, the cover being one solid layer that delineates the microcavity,

a plug forming a unitary piece made of phosphosilicate glass covering only one hole and a part of the cover over the periphery of the hole,

a sealing layer hermetically sealing the microcavity, the microcomponent comprising, under the sealing layer, a plug covering the hole and a part of the cover over the periphery of the hole, the sealing layer being disposed above the plug and the cover, the sealing layer and the plug being formed by distinct materials, wherein the plug is made of phosphosilicate glass materials.

35. (Currently Amended) Microcomponent comprisingcomprising:
a sacrificial layer on a substrate,

a ~~cover~~,cover in which at least one hole is formed, the cover provided over the sacrificial layer and over the substrate at the periphery of the sacrificial layer, a hermetically-sealed microcavity formed by removal of all of the sacrificial layer via the at least one hole, ~~and, on the cover,~~
a plug forming a unitary piece made of polymer covering only one hole and a part of the cover over the periphery of the hole,
~~a sealing layer hermetically sealing the microcavity, the microcomponent comprising, under the sealing layer, a plug covering the hole and a part of the cover over the periphery of the hole, the sealing layer being disposed above the plug and the cover, the sealing layer and the plug being formed by distinct materials, wherein the plug is made of polymer materials.~~

36. (Previously Presented) Method according to claim 35, wherein the geometry of the microcavity is defined by the area of the removed sacrificial layer.